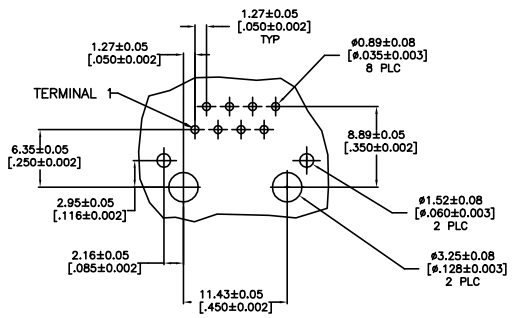
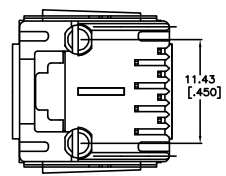
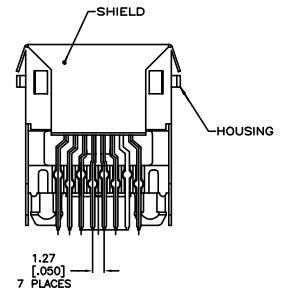
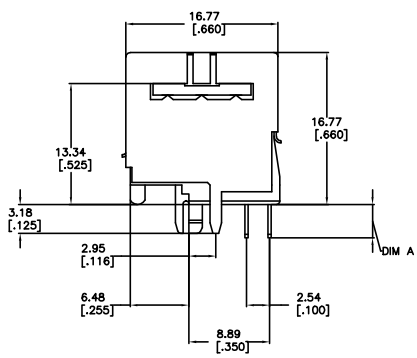
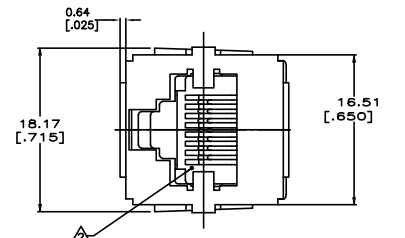
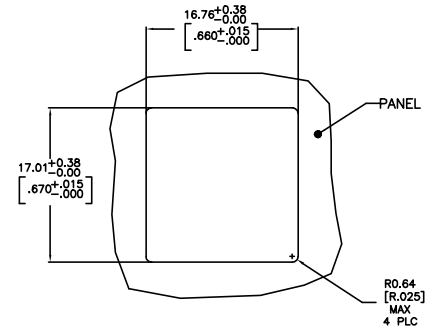


THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION. ALL RIGHTS RESERVED.

REVISIONS			
REV	DATE	DESCRIPTION	BY
E1	05SEP2019	ECO-19-013839	IT SH



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

- 1 MATERIAL:
HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81μm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0μm [.000120] MIN THICK REFLOWED TIN.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3 MATERIAL:
HOUSING – HIGH TEMP THERMOPLASTIC-LCP, COLOR: BLACK
TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81μm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0μm [.000120] MIN THICK REFLOWED TIN.
- 4 RECOMMENDED DIAMETER OF POSITION HOLE ON PCB FOR 5557969-3, 5557969-4 IS 3.175±0.08MM
- 5 SAME AS 5557969-3 BUT RESTRICTED TO CUSTOMNER

MATERIAL	DIM A	PART NUMBER
1	2.79-3.56 [1.25±.015]	5557969-4
4	2.79-3.56 [1.25±.015]	5557969-3
1	2.79-3.30 [1.20±.010]	5557969-2
1	2.79-3.56 [1.25±.015]	5557969-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DESIGNER: A. FERNANDEZ-ROCKI
DIR: J. WESTMAN
CHECKER: S. ELKINGER
DATE: 108-1163

TE Connectivity
MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL

APPLICATOR SPEC: 114-2048
SCALE: 4:1
SHEET: 1 OF 1
REV: E1